

EXAMINER TEXT SEARCH

application # 10 / 661,552.

L Number	Hits	Search Text	DB	Time stamp
-	22	laser adj ablated adj features	USPAT	2004/08/23 11:19
-	754	laser adj ablated	USPAT	2004/08/18 17:45
-	150	(laser adj ablated) and (flush or coplanar)	USPAT	2004/08/18 17:45
-	136	((laser adj ablated) and (flush or coplanar)) not (laser adj ablated adj features)	USPAT	2004/08/20 16:17
-	4776	(circuit adj feature\$1 or pattern\$1 or trace\$1) with (embedded)	USPAT	2004/08/20 16:49
-	523	((circuit adj feature\$1 or pattern\$1 or trace\$1) with (embedded)) and (flush or coplanar)	USPAT	2004/08/20 16:47
-	12	laser adj ablated adj features	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/20 16:48
-	948	(circuit adj feature\$1 or pattern\$1 or trace\$1 or circuitry) with (embedded) with (substrate or board or dielectric adj layer)	USPAT	2004/08/20 16:50
-	240	((circuit adj feature\$1 or pattern\$1 or trace\$1 or circuitry) with (embedded) with (substrate or board or dielectric adj layer)) and laser	USPAT	2004/08/20 16:50
-	206	((circuit adj feature\$1 or pattern\$1 or trace\$1 or circuitry) with (embedded) with (substrate or board or dielectric adj layer)) and laser not ((circuit adj feature\$1 or pattern\$1 or trace\$1) with (embedded)) and (flush or coplanar))	USPAT	2004/08/20 16:51
-	734	(174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (seed adj layer)	USPAT	2004/08/23 11:00
-	1720	(174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (rigid near3 layer)	USPAT	2004/08/23 11:00
-	21	((174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (seed adj layer)) and ((174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (rigid near3 layer))	USPAT	2004/08/23 11:10
-	30	((174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (seed adj layer)) and (second adj dielectric adj layer)	USPAT	2004/08/23 11:11
-	26	((174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (seed adj layer)) and (second adj dielectric adj layer)) not ((174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (seed adj layer)) and ((174/\$.ccls. or 361/\$.ccls. or 29/\$.ccls. or 428/\$.ccls.) and (rigid near3 layer))	USPAT	2004/08/23 11:11
-	34	laser adj ablated adj features	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:20
-	9841	seed adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:20
-	497	(seed adj layer) and ((first adj dielectric) and (second adj dielectric))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:21
-	50	((seed adj layer) and ((first adj dielectric) and (second adj dielectric))) and rigid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 11:25
-	434	(174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and (seed adj layer)	USPAT	2004/09/01 16:04

-	41226	(174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and (board or substrate)	USPAT	2004/09/01 16:05
-	19006	(174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and ((printed adj wiring) or (printed adj circuit))	USPAT	2004/09/01 16:06
-	42431	((174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and (board or substrate)) or ((174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and ((printed adj wiring) or (printed adj circuit)))	USPAT	2004/09/01 16:06
-	405	((174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and (seed adj layer)) and (((174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and (board or substrate)) or ((174/\$.CCLS. OR 29/\$.CCLS. OR 361/\$.CCLS.) and ((printed adj wiring) or (printed adj circuit))))	USPAT	2004/09/01 18:05
-	808	(built adj up or build adj up) with (thin or thickness) with (board or substrate)	USPAT	2004/09/09 14:55
-	53	(built adj up or build adj up) with (thin or thickness) with (board or substrate) and 174/\$.ccls.	USPAT	2004/09/09 16:09
-	64	(built adj up or build adj up) with (thin or thickness) with (board or substrate) and 29/\$.ccls.	USPAT	2004/09/09 15:12
-	48	((built adj up or build adj up) with (thin or thickness) with (board or substrate) and 29/\$.ccls.) not ((built adj up or build adj up) with (thin or thickness) with (board or substrate) and 174/\$.ccls.)	USPAT	2004/09/09 15:12